



Specification of Automotive MLCC

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10C220JB81PNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 22pF, 50V, ±5%, C0G, 0603

• AEC-Q 200 Specified

A. Samsung Part Number

<u>CL</u> <u>10</u> <u>C</u> <u>220</u> <u>J</u> <u>B</u> <u>8</u> <u>1</u> <u>P</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

| 1 | Series | Samsung Multi-layer Ceramic Capacitor | | | | |
|-----|---------------|---------------------------------------|--------|-----------------|------------------|------------|
| 2 | Size | 0603 (inch code) | L: 1.0 | 6 ± 0.1 mm | W: 0.8 ± 0.1 | mm |
| 3 | Dielectric | COG | 8 | Inner electrode | Ni | |
| 4 | Capacitance | 22 pF | | Termination | Cu | |
| (5) | Capacitance | ±5 % | | Plating | Sn 100% | (Pb Free) |
| | tolerance | | 9 | Product | Automotive | |
| 6 | Rated Voltage | 50 V | 100 | Grade code | Standard | |
| 7 | Thickness | 0.8 ± 0.1 mm | 11) | Packaging | Cardboard Typ | e, 7" reel |

B. Reliablility Test and Judgement condition

| | Performance | Test condition | |
|----------------------|--|--|--|
| High Temperature | Appearance : No abnormal exterior appearance | Unpowered, 1000hrs@T=150 ℃ | |
| Exposure | Capacitance Change : | Measurement at 24±2hrs after test conclusion | |
| | within ±2.5% or ±0.25pF whichever is larger | | |
| | Q: 840 min | | |
| | IR : More than 10,000№ or 500№×μF | | |
| | Whichever is Smaller | | |
| Temperature Cycling | Appearance : No abnormal exterior appearance | 1000Cycles | |
| | Capacitance Change : | Measurement at 24±2hrs after test conclusion | |
| | within ±2.5% or ±0.25pF whichever is larger | 1 cycle condition : | |
| | Q: 840 min | -55+0/-3 °C (15±3min) -> Room Temp(1min.) | |
| | IR : More than 10,000№ or 500№×μF | -> 125+3/-0 ℃(15±3min) -> Room Temp(1min.) | |
| | Whichever is Smaller | | |
| Destructive Physical | No Defects or abnormalities | Per EIA 469 | |
| Analysis | | | |
| Moisture Resistance | Appearance : No abnormal exterior appearance | 10Cycles, t=24hrs/cycle | |
| | Capacitance Change : | Heat (25~65 °C) and humidity (80~98%), Unpowered | |
| | within ±2.5% or ±0.25pF whichever is larger | measurement at 24±2hrs after test conclusion | |
| | Q: 330 min | | |
| | IR : More than 10,000MΩ or 500MΩ×μF | | |
| | Whichever is Smaller | | |
| Humidity Bias | Appearance : No abnormal exterior appearance | 1000hrs 85 ℃/85%RH, Rated Voltate and 1.3~1.5V, | |
| | Capacitance Change : | Add 100kohm resistor | |
| | within ±2.5% or ±0.25pF whichever is larger | Measurement at 24±2hrs after test conclusion | |
| | Q: 173.33 min | The charge/discharge current is less than 50mA. | |
| | IR : More than 500 MΩ or 25 MΩ×μF | | |
| | Whichever is Smaller | | |
| High Temperature | Appearance : No abnormal exterior appearance | 1000hrs @ TA=125 ℃, 200% Rated Voltage, | |
| Operating Life | Capacitance Change : | Measurement at 24±2hrs after test conclusion | |
| | within ±3.0% or ±0.3pF whichever is larger | The charge/discharge current is less than 50mA. | |
| | Q: 330 min | | |
| | IR : More than 10,000№ or 500№×μF | | |
| | Whichever is Smaller | | |

| | Performance | Test condition | | | |
|---------------------|---|--|--|--|--|
| External Visual | No abnormal exterior appearance | Microscope (´10) | | | |
| Physical Dimensions | Within the specified dimensions | Using The calipers | | | |
| Mechanical Shock | Appearance: No abnormal exterior appearance Capacitance Change: within ±2.5% or ±0.25pF whichever is larger Q, IR: initial spec. | Three shocks in each direction should be applied along 3 mutually perpendicular axes of the test specimen (18 shocks) Peakvalue Duration Wave Velocity 1,500G 0.5ms Half sine 4.7m/sec. | | | |
| Vibration | Appearance: No abnormal exterior appearance Capacitance Change: within ±2.5% or ±0.25pF whichever is larger Q, IR: initial spec. | 5g's for 20min., 12cycles each of 3 orientations, Use 8"x5" PCB 0.031" Thick 7 secure points on one long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10~2000 Hz. | | | |
| Resistance to | Appearance : No abnormal exterior appearance | Solder pot : 260±5 ℃, 10±1sec. | | | |
| Solder Heat | Capacitance Change : within ±2.5% or ±0.25pF whichever is larger Q, IR : initial spec. | | | | |
| Thermal Shock | Appearance: No abnormal exterior appearance Capacitance Change: within ±2.5% or ±0.25pF whichever is larger Q, IR: initial spec. | -55 °C/+125 °C. Note: Number of cycles required-300, Maximum transfer time-20 sec, Dwell time-15min. Air-Air | | | |
| ESD | Appearance: No abnormal exterior appearance Capacitance Change: within ±2.5% or ±0.25pF whichever is larger Q, IR: initial spec. | AEC-Q200-002 | | | |
| Solderability | 95% of the terminations is to be soldered evenly and continuously | a) Preheat at 155 °C for 4 hours, Immerse in solder for 5s at 245±5 °C b) Steam aging for 8 hours, Immerse in solder for 5s at 245±5 °C c) Steam aging for 8 hours, Immerse in solder for 120s at 260±5 °C solder: a solution ethanol and rosin | | | |
| Electrical | Capacitance : Within specified tolerance | The Capacitance /Q should be measured at 25 ℃, | | | |
| Characterization | Q: 840 max. IR(25℃): More than 100,000 MΩ or 1,000 MΩ×μF IR(125℃): More than 10,000 MΩ or 100 MΩ×μF Whichever is Smaller | 1Mb±10%, 0.5~5Vrms I.R. should be measured with a DC voltage not exceeding Rated Voltage @25℃, @125℃ for 60~120 sec. Dielectric Strength: 250% of the rated voltage for 1~5 seconds | | | |
| Board Flex | Dielectric Strength Appearance : No abnormal exterior appearance Capacitance Change : within ±5.0% or ±0.5pF whichever is larger | Bending to the limit (3mm) for 5 seconds | | | |
| Terminal | Appearance : No abnormal exterior appearance | 10N, for 60±1 sec. | | | |
| Strength(SMD) | Capacitance Change : within ±2.5% or ±0.25pF whichever is larger | | | | |
| Beam Load | Destruction value should not be exceed Chip Length < 2.5mm a) Chip Thickness > 0.5mm : 20N b) Chip Thickness ≤ 0.5mm : 8N | Beam speed 0.5±0.05mm/sec | | | |
| Temperature | COG | | | | |
| Characterisitcs | (From -55 $^\circ\!$ | | | | |

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}\!\!\!\mathrm{C}$, 10sec. Max)

Meet IPC/JEDEC J-STD-020 D Standard

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.